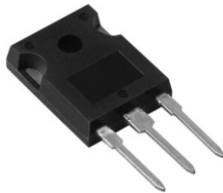
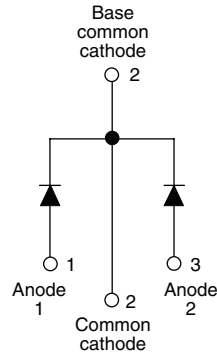


## HEXFRED®

### Ultrafast, Soft Recovery Diode, 2 x 8 A



**TO-247AC**



#### FEATURES

- Ultrafast recovery
- Ultrasoft recovery
- Very low  $I_{RRM}$
- Very low  $Q_{rr}$
- Specified at operating conditions
- Designed and qualified for industrial level

#### BENEFITS

- Reduced RFI and EMI
- Reduced power loss in diode and switching transistor
- Higher frequency operation
- Reduced snubbing
- Reduced parts count

#### DESCRIPTION

HFA16PA60C is a state of the art center tap ultrafast recovery diode. Employing the latest in epitaxial construction and advanced processing techniques it features a superb combination of characteristics which result in performance which is unsurpassed by any rectifier previously available. With basic ratings of 600 V and 8 A per leg continuous current, the HFA16PA60C is especially well suited for use as the companion diode for IGBTs and MOSFETs. In addition to ultrafast recovery time, the HEXFRED® product line features extremely low values of peak recovery current ( $I_{RRM}$ ) and does not exhibit any tendency to “snap-off” during the  $t_b$  portion of recovery. The HEXFRED features combine to offer designers a rectifier with lower noise and significantly lower switching losses in both the diode and the switching transistor. These HEXFRED advantages can help to significantly reduce snubbing, component count and heatsink sizes. The HEXFRED HFA16PA60C is ideally suited for applications in power supplies and power conversion systems (such as inverters), motor drives, and many other similar applications where high speed, high efficiency is needed.

#### PRODUCT SUMMARY

$V_R$	600 V
$V_F$ at 8 A at 25 °C	1.7 V
$I_{F(AV)}$	2 x 8 A
$t_{rr}$ (typical)	18 ns
$T_J$ (maximum)	150 °C
$Q_{rr}$	65 nC
$di_{(rec)}/dt$	240 A/μs

#### ABSOLUTE MAXIMUM RATINGS

PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS
Cathode to anode voltage	$V_R$		600	V
Maximum continuous forward current	$I_F$	$T_C = 100\text{ °C}$	8	A
			16	
Single pulse forward current	$I_{FSM}$		60	
Maximum repetitive forward current	$I_{FRM}$		24	
Maximum power dissipation	$P_D$	$T_C = 25\text{ °C}$	36	W
		$T_C = 100\text{ °C}$	14	
Operating junction and storage temperature range	$T_J, T_{Stg}$		- 55 to + 150	°C

ELECTRICAL SPECIFICATIONS PER LEG (T <sub>J</sub> = 25 °C unless otherwise specified)							
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNITS
Cathode to anode breakdown voltage	V <sub>BR</sub>	I <sub>R</sub> = 100 μA		600	-	-	V
Maximum forward voltage	V <sub>FM</sub>	I <sub>F</sub> = 8.0 A	See fig. 1	-	1.4	1.7	
		I <sub>F</sub> = 16 A		-	1.7	2.1	
		I <sub>F</sub> = 8.0 A, T <sub>J</sub> = 125 °C		-	1.4	1.7	
Maximum reverse leakage current	I <sub>RM</sub>	V <sub>R</sub> = V <sub>R</sub> rated	See fig. 2	-	0.3	5.0	μA
		T <sub>J</sub> = 125 °C, V <sub>R</sub> = 0.8 x V <sub>R</sub> rated		-	100	500	
Junction capacitance	C <sub>T</sub>	V <sub>R</sub> = 200 V	See fig. 3	-	10	25	pF
Series inductance	L <sub>S</sub>	Measured lead to lead 5 mm from package body		-	8.0	-	nH

DYNAMIC RECOVERY CHARACTERISTICS PER LEG (T <sub>J</sub> = 25 °C unless otherwise specified)							
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNITS
Reverse recovery time See fig. 5, 6 and 16	t <sub>rr</sub>	I <sub>F</sub> = 1.0 A, dI <sub>F</sub> /dt = 200 A/μs, V <sub>R</sub> = 30 V		-	18	-	ns
	t <sub>rr1</sub>	T <sub>J</sub> = 25 °C	I <sub>F</sub> = 8.0 A dI <sub>F</sub> /dt = 200 A/μs V <sub>R</sub> = 200 V	-	37	55	
	t <sub>rr2</sub>	T <sub>J</sub> = 125 °C		-	55	90	
Peak recovery current See fig. 7 and 8	I <sub>RRM1</sub>	T <sub>J</sub> = 25 °C		-	3.5	5.0	A
	I <sub>RRM2</sub>	T <sub>J</sub> = 125 °C		-	4.5	8.0	
Reverse recovery charge See fig. 9 and 10	Q <sub>rr1</sub>	T <sub>J</sub> = 25 °C		-	65	138	nC
	Q <sub>rr2</sub>	T <sub>J</sub> = 125 °C		-	124	360	
Peak rate of fall recovery current during t <sub>b</sub> See fig. 11 and 12	di <sub>(rec)M</sub> /dt1	T <sub>J</sub> = 25 °C		-	240	-	A/μs
	di <sub>(rec)M</sub> /dt2	T <sub>J</sub> = 125 °C		-	210	-	

THERMAL - MECHANICAL SPECIFICATIONS						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Lead temperature	T <sub>lead</sub>	0.063" from case (1.6 mm) for 10 s	-	-	300	°C
Junction to case, single leg conducting	R <sub>thJC</sub>		-	-	3.5	K/W
Junction to case, both leg conducting			-	-	1.75	
Thermal resistance, junction to ambient	R <sub>thJA</sub>	Typical socket mount	-	-	40	
Thermal resistance, case to heatsink	R <sub>thCS</sub>	Mounting surface, flat, smooth and greased	-	0.25	-	
Weight			-	6.0	-	g
			-	0.21	-	oz.
Mounting torque			6.0 (5.0)	-	12 (10)	kgf · cm (lbf · in)
Marking device		Case style TO-247AC (JEDEC)	HFA16PA60C			



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Vishay High Power Products

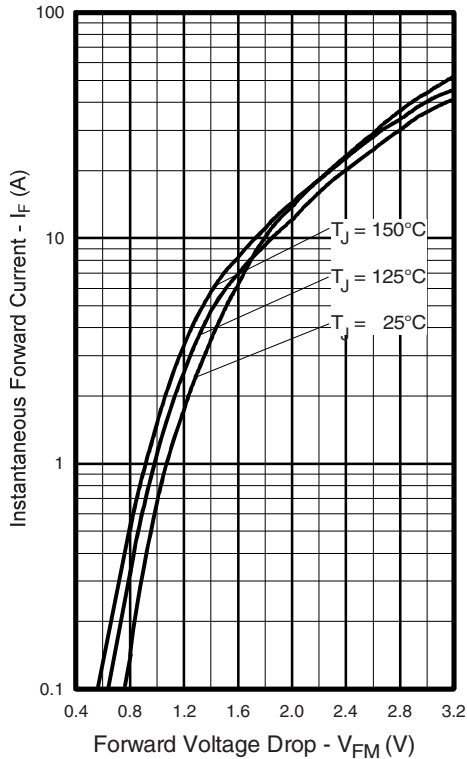


Fig. 1 - Maximum Forward Voltage Drop vs. Instantaneous Forward Current (Per Leg)

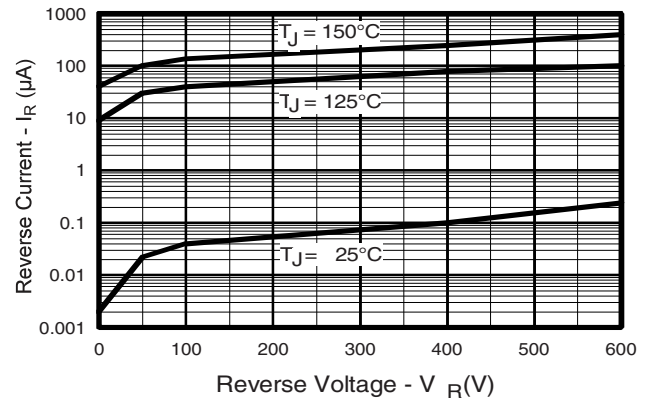


Fig. 2 - Typical Reverse Current vs. Reverse Voltage (Per Leg)

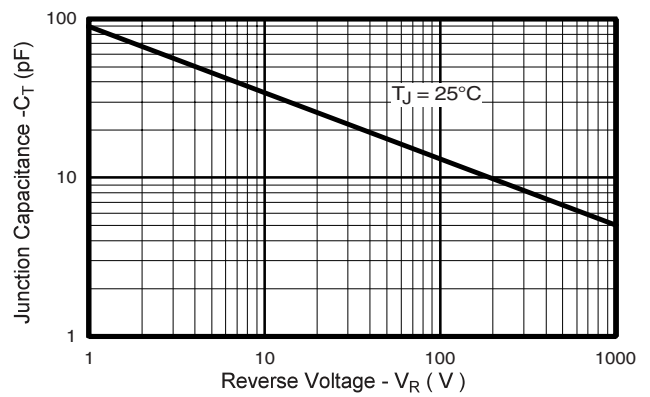


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage (Per Leg)

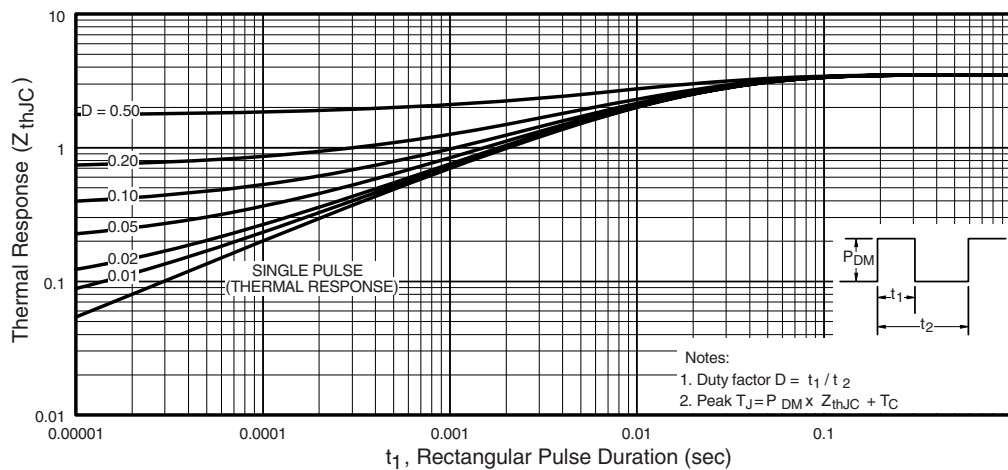
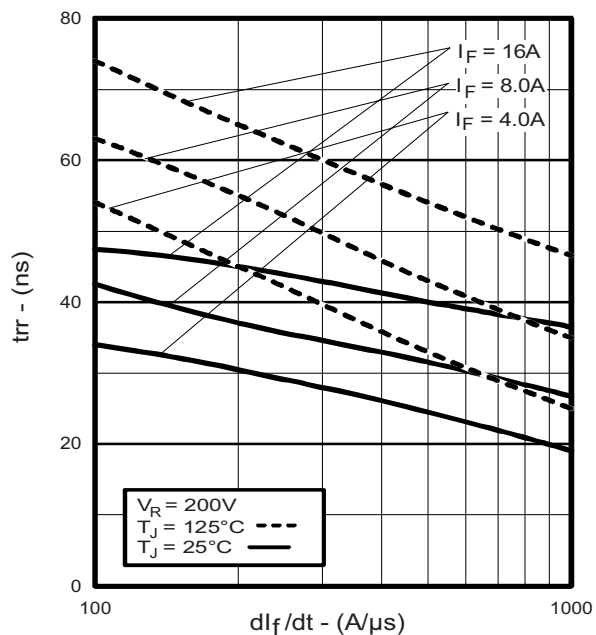
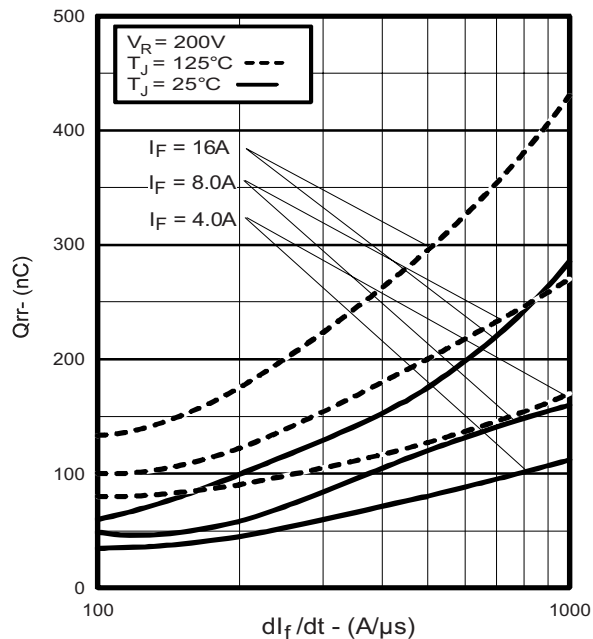
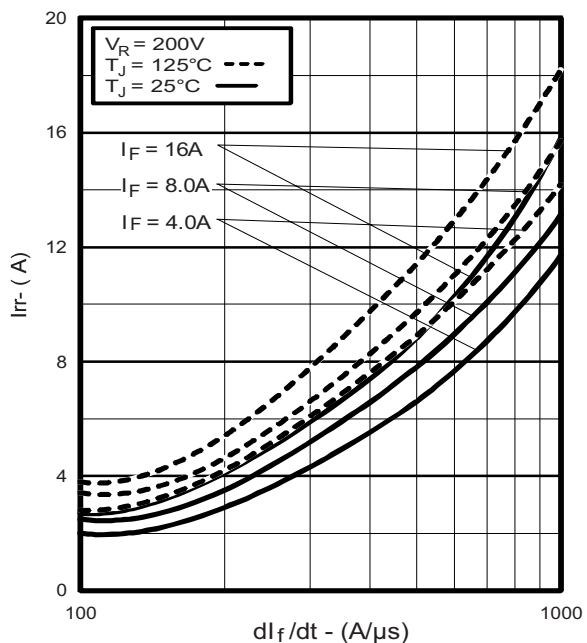
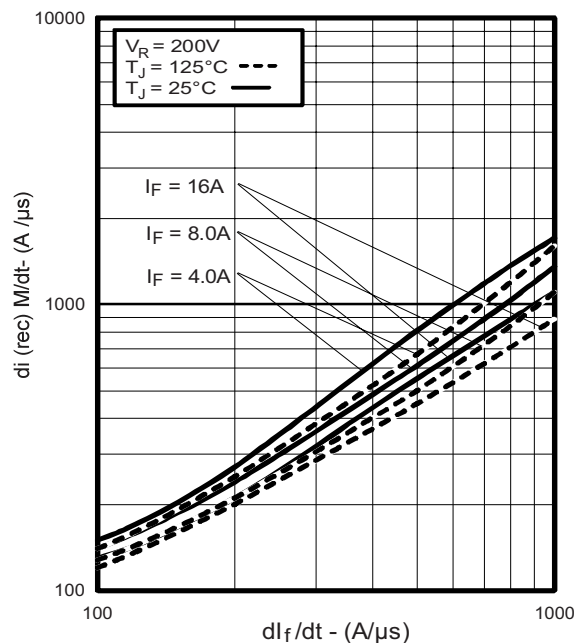


Fig. 4 - Maximum Thermal Impedance  $Z_{thJC}$  Characteristics (Per Leg)

Fig. 5 - Typical Reverse Recovery Time vs.  $dI_F/dt$  (Per Leg)Fig. 7 - Typical Stored Charge vs.  $dI_F/dt$  (Per Leg)Fig. 6 - Typical Recovery Current vs.  $dI_F/dt$  (Per Leg)Fig. 8 - Typical  $dI_{(rec)}M/dt$  vs.  $dI_F/dt$  (Per Leg)

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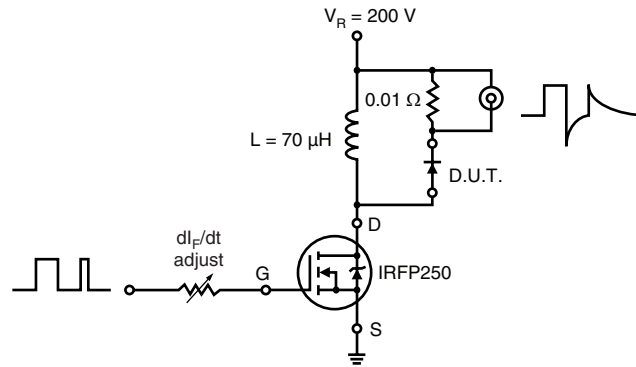


Fig. 9 - Reverse Recovery Parameter Test Circuit

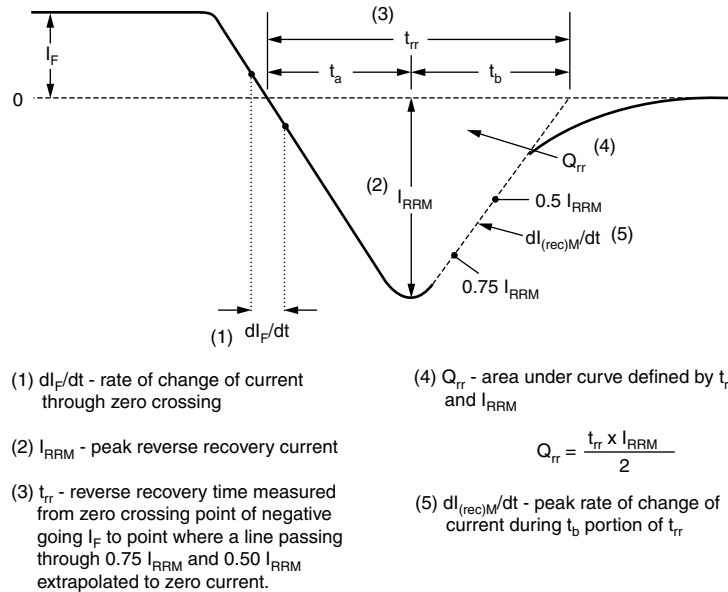


Fig. 10 - Reverse Recovery Waveform and Definitions

**ORDERING INFORMATION TABLE**

Device code	HF	A	16	PA	60	C	-
	1	2	3	4	5	6	7

- |   |   |  |
|---|---|--|
| 1 | - | HEXFRED® family  |
| 2 | - | Process designator: A = Subs. elec. irradi.<br>B = Subs. platinum  |
| 3 | - | Current rating (16 = 16 A)   |
| 4 | - | Package outline (PA = TO-247, 3 pins)  |
| 5 | - | Voltage rating (60 = 600 V)  |
| 6 | - | Configuration (C = Center tap common cathode)  |
| 7 | - | <ul style="list-style-type: none"> <li>• None = Standard production</li> <li>• PbF = Lead (Pb)-free</li> </ul> |

LINKS TO RELATED DOCUMENTS	
Dimensions	<a href="http://www.vishay.com/doc?95223">http://www.vishay.com/doc?95223</a>
Part marking information	<a href="http://www.vishay.com/doc?95226">http://www.vishay.com/doc?95226</a>



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